

## **Abstract of Japanese Patent Office Gazette**

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### **SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF**

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**PURPOSE:** To prevent cracks from being produced in a molding resin even in working environment where heat acts by a method wherein upper and lower edges in a periphery of a bed and upper and lower edges at a connection end to a bonding wire of a lead are formed in such a way that their cross sections are of protruding arc shapes.

**CONSTITUTION:** This device includes the following: a semiconductor pellet 1; a bed 2 which has a required thickness for mounting this semiconductor pellet; a lead 3 which connects an element inside the semiconductor pellet 1 to the outside. The lead 3 is connected electrically to the semiconductor pellet 1 by using a bonding wire 4. When sharp parts 2a are formed at an upper edge and a lower edge in a peripheral part of the bed 2, a crack 5a is stretched from the sharp parts 2a when heat is applied during a mounting operation. Parts 20, 30 whose cross sections are protruding arc shapes are formed in parts where the sharp parts existed in a conventional method. By this setup, it is possible to completing restrain a crack from being produced in a region which has been regarded as safe in the conventional method.